EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	36	"5302547"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:34
L3	309	(interconnect or via) and sensor and flexible with polymer with substrate and polymer with dielectric	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:37
L4	63	(interconnect or via) and sensor and flexible with polymer with substrate and polymer with dielectric and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:38
L5	8	(interconnect or via) and sensor and flexible with polymer with substrate and polymer with dielectric and @PY<"2004" and plasma with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:38
L6	63	(interconnect or via) and sensor and flexible with polymer with substrate and polymer with dielectric and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:44
L7	13	(interconnect or via) and flexible with polymer with substrate and polymer with dielectric and @PY<"2004" and plasma with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:49
L8	5	(interconnect or via) and flexible with polymer with substrate and polymer with dielectric and @PY<"2004" and plasma with adhesion not L5	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:49
L9	849	@PY<"2004" and plasma with adhesion and interconnect$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
L10	4	@PY<"2004" and polymer with metal with plasma with adhesion and interconnect$3 with device	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
L11	92	@PY<"2004" and polymer with metal with plasma with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18

L12	0	@PY<"2004" and polymer with metal with plasma with adhesion with device	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
L13	48	@PY<"2004" and polymer with metal with plasma with adhesion and device	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
L14	19	@PY<"2004" and polymer with metal with plasma with adhesion and (electrical or electronic or semiconductor) with device	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:19
L15	2	(("4,765,860") or ("4,382,101")).PN.	USPAT; USOCR	OR	OFF	2009/05/06 16:24
L16	490	SiN with hard mask and mask with thickness	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:39
L17	113	SiN with hard mask and mask with thickness and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:39
L18	0	SiN with hard mask and mask with thickness with suitable and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:40
L19	1	SiN with hard mask and mask with thickness with variable and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:41
L20	0	SiN with hard mask and mask with thickness with designand @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:41
L21	0	SiN with hard mask and mask with thickness with design and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:41
L22	10	SiN with hard mask and mask with thickness with effect$8 and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:41

L23	10	SiN with hard mask and mask with thickness with etch and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:43
L24	48	hard mask and mask with thickness with effect$8 and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:46
L25	16	hard mask and mask with thickness with varied and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:48
S1	16	"5294290"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 14:43
S2	1	("5294290").PN.	USPAT; USOCR	OR	OFF	2009/05/01 14:43
S3	1	("6662439").PN.	USPAT; USOCR	OR	OFF	2009/05/01 14:56
S4	87	laser ablation with sacrificial	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:11
S5	13	laser ablation with sacrificial and (PTFE or fluorin$ or teflon)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:12
S6	62	laser ablation with sacrificial and (PVD or PECVD or deposition or CVD)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:13
S7	7434	laser ablation and @PY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:32
S8	4766	laser ablation and @AY>="2001"<="2002"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:33
S9	3326	laser ablation and @AY>="2000"<="2001"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:33

S10	126	laser ablation and metal with insulator and @AY>="2000"<="2001"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:34
S11	351	laser ablation and metal with layer with insulator and (PECVD or PVD or CVD or vapor deposition)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:36
S12	164	laser ablation and metal with layer with insulator and (PECVD or PVD or CVD or vapor deposition) and (intermediat$3 or sacrific$5 or tie)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:37
S13	48	laser ablation and metal with layer with insulator and (PECVD or PVD or CVD or vapor deposition) and (intermediat$3 or sacrific$5 or tie) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:37
S14	3	laser ablation and metal with layer with (PVD or physical vapor deposition) with insulator with (PECVD or CVD or plasma or vapor deposition) and (intermediat$3) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:41
S15	9	laser ablation and metal with layer with (PVD or physical vapor deposition) and insulator with (PECVD or CVD or plasma or vapor deposition) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:41
S16	1152	laser ablation and (conductor or metal) with (dielectric or insulator or "sio.sub.2" or silicon oxide or silicon dioxide) and (PVD or PECVD or CVD or vapor deposition) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:43
S17	1690	204/157.15,157.41,157.61.ccls. or 216/94,95.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:44
S18	3	S16 and S17	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:44
S19	24	laser ablation and (conductor or metal) with (dielectric or insulator or "sio.sub.2" or silicon oxide or silicon dioxide) with (PTFE or polytetrafluoroethylene or fluorin$5) and (PVD or PECVD or CVD or vapor deposition) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:54
S20	2	(("4987006") or ("4752455")).PN.	USPAT; USOCR	OR	OFF	2009/05/01 16:22

S21	39	("4783695" | "4835704" | "4894115" | "5073814" | "5130229" | "5173442").PN. OR ("5302547"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/05/01 17:32
S22	646	flexible and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:02
S23	310	flexible with (substrate or circuit) and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:03
S24	36	flexible with (substrate or circuit) and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum) and electron beam	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:03
S25	5	flexible with (substrate or circuit) and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum) and electron beam and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:03
S26	60	flexible with (substrate or circuit) and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:14
S27	2	"5073814".pn.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/05 16:48

5/6/2009 5:06:20 PM
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